## LNJ026X8ARA

### Surface Mounting Chip LED

**UTSS Type** 

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	40	mW	
Forward current	$I_{\mathrm{F}}$	10	mA	
Pulse forward current *	$I_{FP}$	40	mA	
Reverse voltage	V <sub>R</sub>	5	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

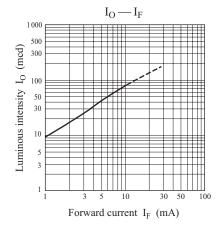
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

#### ■ Lighting Color

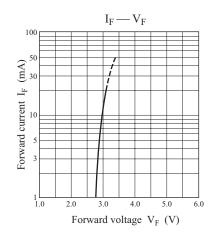
• White

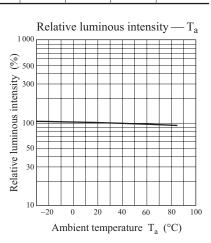
### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

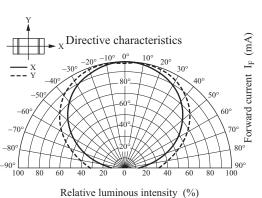
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	Io	$I_F = 5 \text{ mA}$	24	40	81	mcd
Reverse current	$I_R$	$V_R = 5 V$			10	μΑ
Forward voltage	$V_{\rm F}$	$I_F = 5 \text{ mA}$		2.9	3.2	V
Chromaticity coordinates —	х	$I_F = 5 \text{ mA}$	0.229		0.302	_
	у	$I_F = 5 \text{ mA}$	0.215		0.311	_

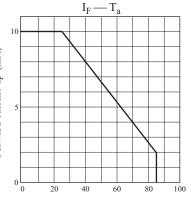


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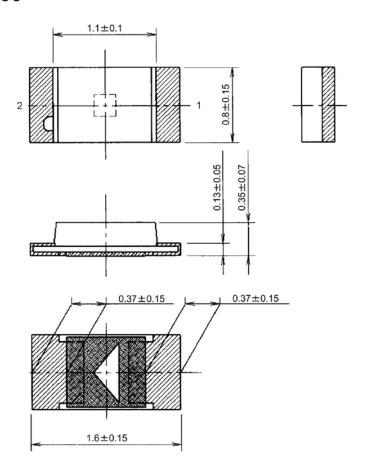
Ambient temperature T<sub>a</sub> (°C)

1

**Panasonic** 

■ Package (Unit: mm)

## KLTFTN2K2600



- Pin name
  - 1: Anode
  - 2: Cathode

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